PATENT

#13
105
J. mcmillan
12/8/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application Of:

Fujio Kuwako

Application No.: Not Assigned

Filed: Not Assigned

For: Method For Producing Multi-Layer Printed Wiring Boards Having Blind Vias

Atty. Docket No.: 47163-00018USD1

Examiner: Not Assigned

Group Art Unit: Not Assigned

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231, on June 9, 2000

Signature: Graciela P. O'Leary

INFORMATION DISCLOSURE
STATEMENT UNDER 37 C.F.R. §§ 1.97 AND 1.98

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In compliance with the duty of disclosure under 37 C.F.R. § 1.56, it is respectfully requested that this Information Disclosure Statement be entered, and the references listed on enclosed Form PTO-1449 be considered by the Examiner and made of record. Copies of the listed references are not enclosed, since they were submitted to the Patent and Trademark Office in the parent application, Serial No. 09/229,225.

In accordance with 37 C.F.R. §§ 1.97(g) and (h), this Information Disclosure Statement is not to be construed as a representation that a search has been made, or an admission that the information disclosed is, or is considered to be, prior art with respect to the present application or material to patentability, as defined in 37 C.F.R. § 1.56.

This Information Disclosure Statement is being filed prior to receipt of a first Office Action reflecting an examination on the merits and, hence, is believed to be timely in accordance with 37 C.F.R. § 1.97(b). Accordingly, no fee is believed to be due. Should any fee be deemed necessary (except payment of the issue fee), however, the Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment, to Deposit Account No. 10-0447/47163-00018USD1. A duplicate copy of this Statement is enclosed for that purpose.

Respectfully submitted,

Date: 4/9/07

Harold N. Wells
Reg. No. 26,044
Jenkens & Gilchrist
1445 Ross Avenue
Suite 3200
Dallas, Texas 75202-2799
(312) 744-0090
For the Applicant

Form PTO-1449 (modified)	Atty. Docket No. 47163-00018USD1	Serial No. Not Assigned
List of Patents and Publications for Applicant's **INFORMATION DISCLOSURE STATEMENT**	Applicant Fujio Kuwako	
Page 1 of 1	Filing Date: Not Assigned	Group: Not Assigned

U.S. Patent Documents

Exam. Init.	Ref. Des.	Document Number	Date	Name	Class	Sub Class	Filing Date if App.
	A01	5,403,672	04/1995	Urasaki et al.	428	607	
	A02						
	A03						
	A04						
	A05						

Foreign Patent Documents

Exam. Init.	Ref. Des.	Document Number	Date	Country	Class	Sub Class	Translation Yes/No
	B01	WO97/41713	11/1997	PCT	H05K	3/02	N/A
	B02	Hei 4-3676	1/1992	Japan	H05K	3/46	Abstract
	B03						

Other Art (Including Author, Title, Date Pertinent Pages, Etc.)

Exam. Init.	Ref. Des.	Citation
	C01	"A Flexible Production Laser System for Blind Via Drilling," Anton Kitai and Jim Morrison, Lumonics, Kanata, Ontario Canada; from brochure *Proceedings of the Technical Conference Expo '98*, 4 pgs.; 1998
	C02	"CO_2 Laser Drilling Technology for Glass Fabrics Base Copper Clad Laminate,: Morio, Gaku, Hidenori Kimbara Nobuyuki Ikeguchi, Yoshihiro Kato, Mitsubishi Gas Chemical Company, Inc., Toyko, Japan; from brochure *Proceedings of the Technical Conference Expo '98*, 4 pgs; 1998 ✓
	C03	Kestenbaum, Ami, et al., "Laser Drilling Of Microvias In Epoxy-Glass Printed Circuit Boards," *IEEE Transactions On Components, Hybrids, and Manufacturing Technology*, Volume 13, No. 4, pp. 1055-1062 (December 1990)
	C04	Pargellis, A. N., et al., "Formation of Microvias In Eposy-Glass Composites By Laser Ablation," *Optics & Laser Technology*, Volume 22, No. 3, pp. 205-207 (June 1990) ✓

EXAMINER:	DATE CONSIDERED:

EXAMINER: INITIAL IF REFERENCE CONSIDERED, WHETHER OR NOT CITATION IS IN CONFORMANCE WITH MPEP609; DRAW LINE THROUGH CITATION IF NOT IN CONFORMANCE AND NOT CONSIDERED. INCLUDE COPY OF THIS FORM WITH NEXT COMMUNICATION TO APPLICANT.